

### Description

The SX80N03NF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = 30V$   $I_D = 80A$

$R_{DS(ON)} < 3.8m\Omega$   $V_{GS}=10V$

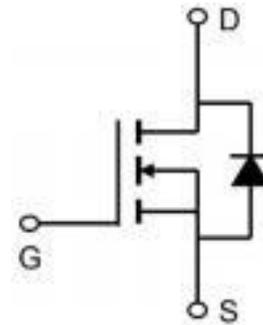
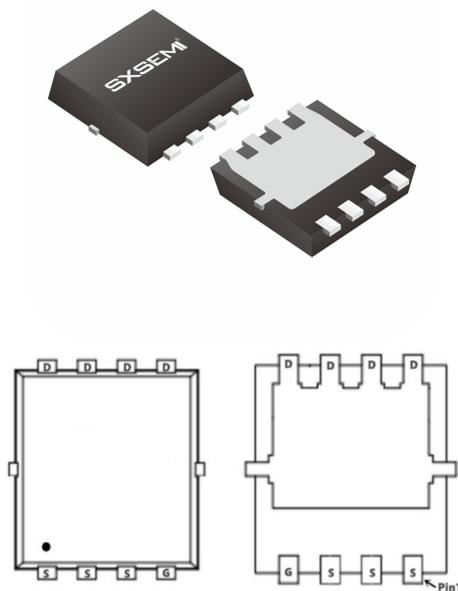
### Application

Battery protection

Load switch

Uninterruptible power supply

### PDFN5\*6-8L



### Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	80	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	65	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	360	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	144.7	mJ
$I_{AS}$	Avalanche Current	53.8	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	43.4	W
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.67	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	25	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	2.3	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	33	-	V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> = 0V,	-	-	1.0	μA
IGSS	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.5	2.5	V
RDS(on)	Static Drain-Source on-Resistance note3	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	2.5	3.5	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	4.3	6.0	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f = 1.0MHz	-	2680	-	pF
C <sub>oss</sub>	Output Capacitance		-	393	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	330	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V	-	30	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	7.2	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	10.4	-	nC
td(on)	Turn-on Delay Time	V <sub>DS</sub> =15V, I <sub>D</sub> =30A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V	-	23	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	28	-	ns
td(off)	Turn-off Delay Time		-	74	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	36	-	ns
IS	Maximum Continuous Drain to Source Diode Forward Current		-	-	120	A
ISM	Maximum Pulsed Drain to Source Diode Forward Current		-	-	400	A
VSD	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> =30A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =20A, dI/dt=100A/μs	-	28	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	21	-	nC

**Note :**

- 1、 The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、 The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=53.8A
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

Typical Characteristics

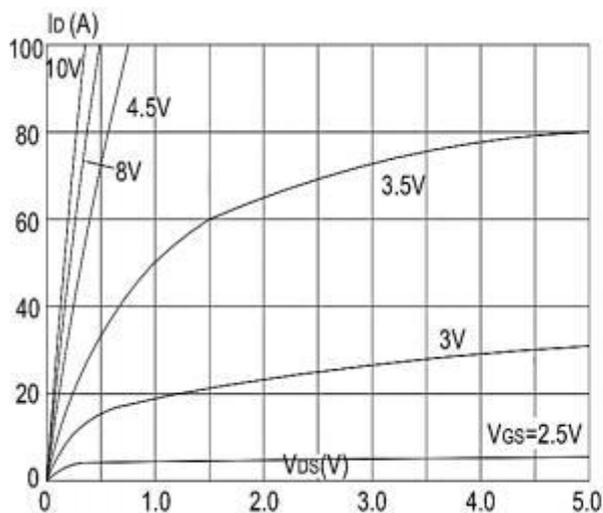


Figure 1: Output Characteristics

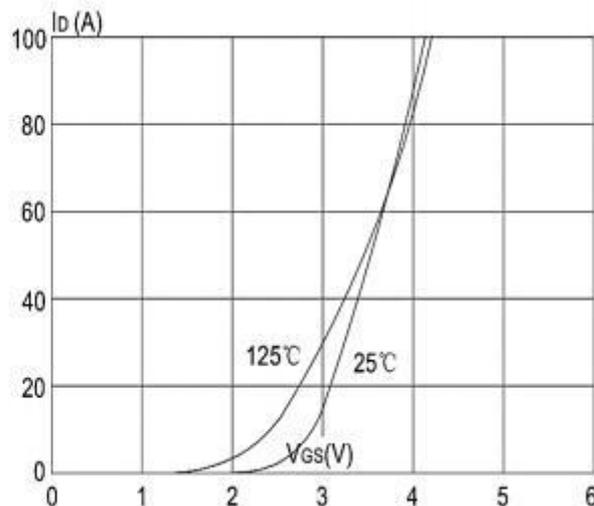


Figure 2: Typical Transfer Characteristics

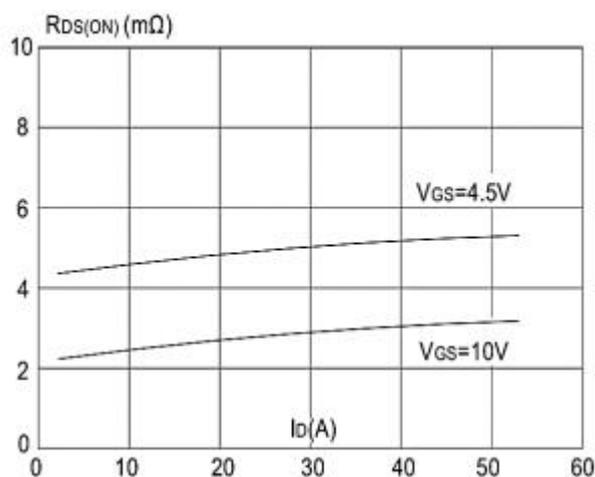


Figure 3: On-resistance vs. Drain Current

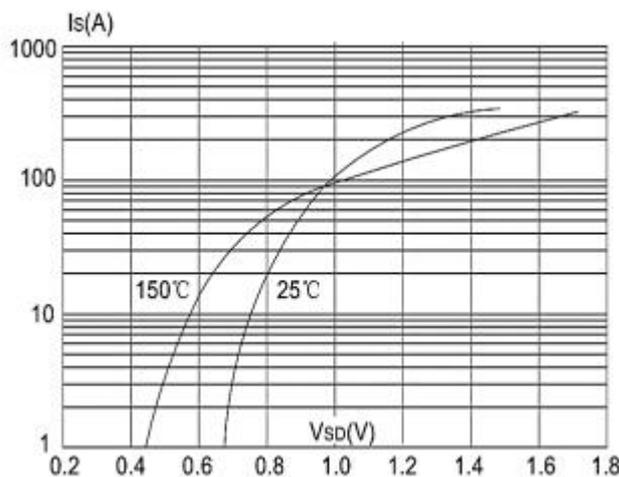


Figure 4: Body Diode Characteristics

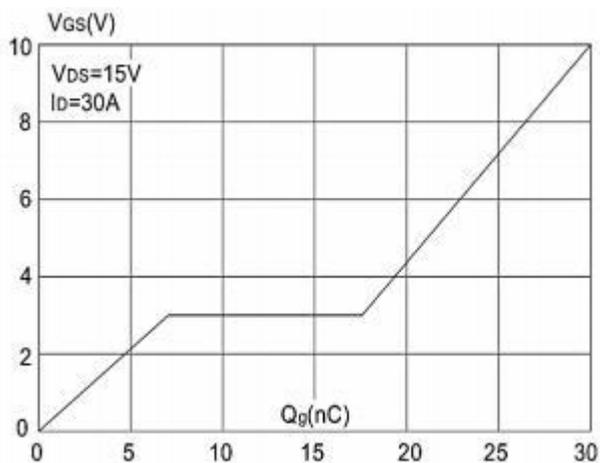


Figure 5: Gate Charge Characteristics

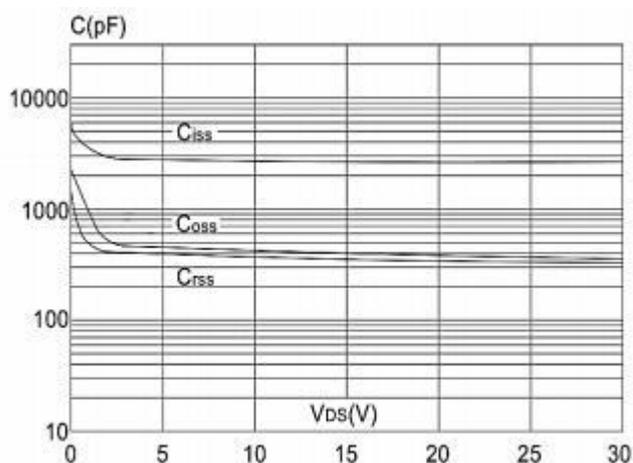


Figure 6: Capacitance Characteristics

Typical Characteristics

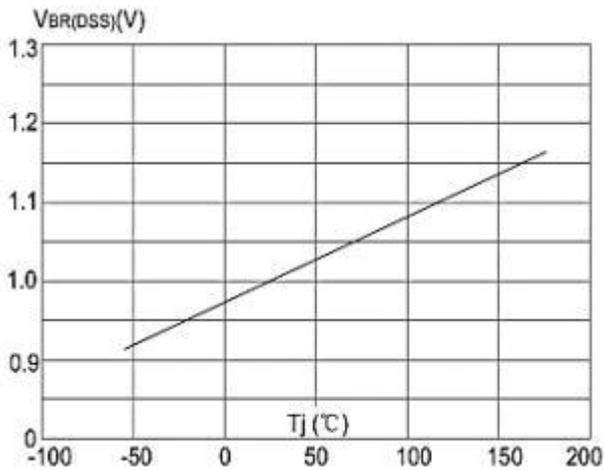


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

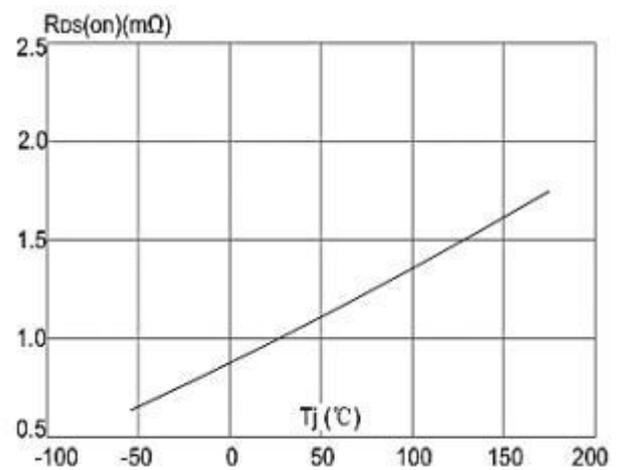


Figure 8: Normalized on Resistance vs. Junction Temperature

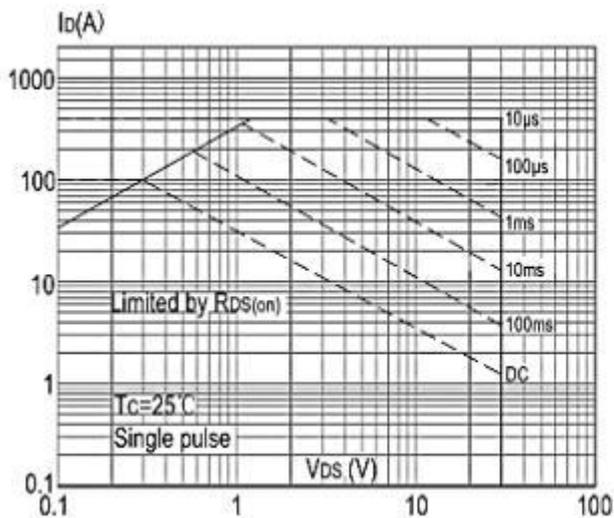


Figure 9: Maximum Safe Operating Area vs. Case Temperature

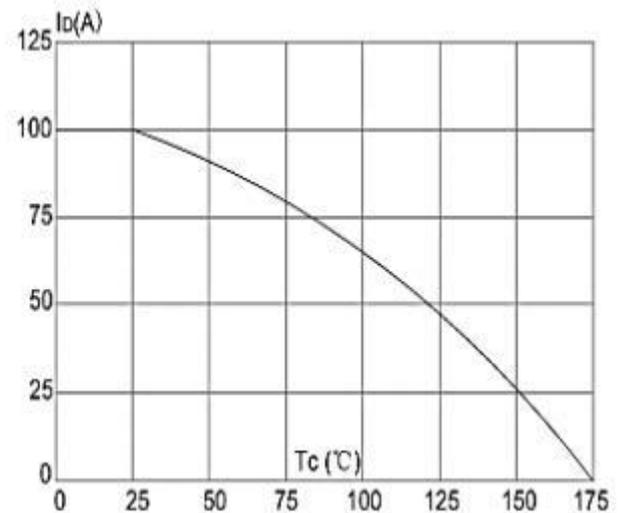


Figure 10: Maximum Continuous Drain Current

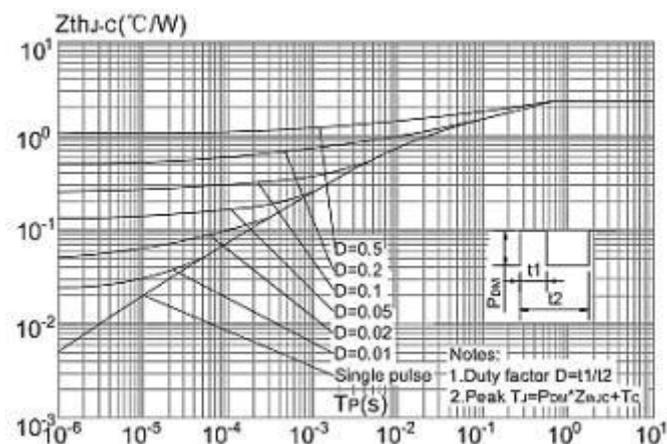
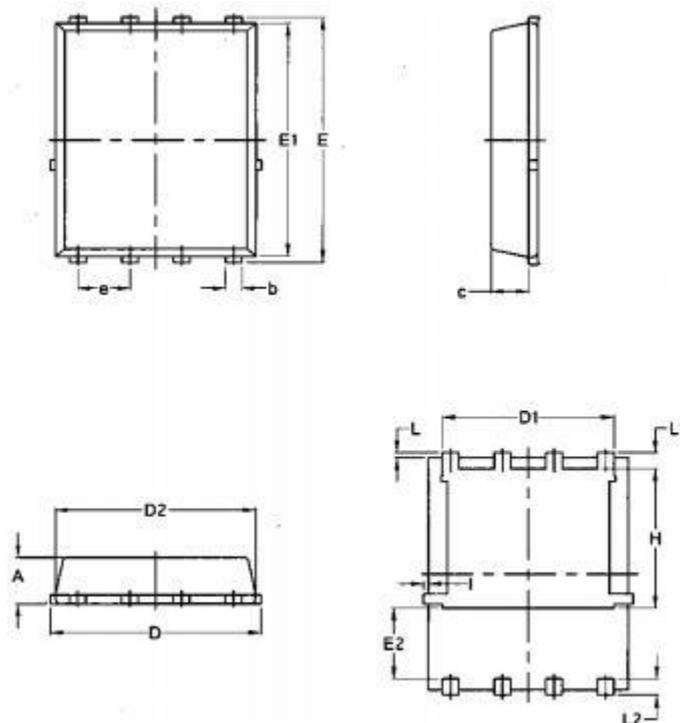


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

**Package Mechanical Data-PDFN5\*6-8L-JQ Single**


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN5*6-8L		5000